

ABSTRACT

A printed circuit board assembly adapted for immersion cooling is disclosed. The assembly includes a first circuit board having a first device side with a first portion configured to mount a first plurality of semiconductor devices. A second
5 circuit board having a second device side with a second portion configured to mount a second plurality of semiconductor devices is disposed in confronting parallel relationship to the first circuit board. The assembly further includes a border element interposed between the first and second boards and disposed around the respective first and second portions. The border element cooperates with the first and second
10 boards to form a liquid-tight container. An inlet formed in the border receives an electrically nonconducting liquid that is subsequently discharged through an outlet.

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